




<b>PCN Number:</b>	20191211001.1			<b>PCN Date:</b>	Jan. 23, 2020				
<b>Title:</b>	Qualification of UTL3 as an additional AT site for Select Devices								
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services						
<b>Proposed 1<sup>st</sup> Ship Date:</b>	April 23, 2020	<b>Estimated Sample Availability:</b>	Date provided at sample request						
<b>Change Type:</b>									
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site				
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material				
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process				
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site				
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials				
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process				
<b>PCN Details</b>									
<b>Description of Change:</b>									
Texas Instruments is pleased to announce the qualification of UTL3 as an additional assembly site for the list of devices below. There are no construction differences between the current and new site.									
<b>Reason for Change:</b>									
Continuity of Supply									
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>									
None									
<b>Anticipated impact on Material Declaration</b>									
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>						
<b>Changes to product identification resulting from this PCN:</b>									
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>						
UTAC1	NSE	THA	Bangkok						
<b>UTAC3</b>	<b>UT3</b>	<b>THA</b>	<b>Chachoengsao</b>						
Sample product shipping label (not actual product label)									
   <div style="display: flex; justify-content: space-between;"> <div style="width: 30%;"> <p>MADE IN: Malaysia 2DC: 2Q:</p> <table border="1" style="font-size: small;"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p> </div> <div style="width: 65%;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>						MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL 2 /260C/1 YEAR	SEAL DT								
MSL 1 /235C/UNLIM	03/29/04								
<b>Product Affected:</b>									
BQ24308DSGR	INA210AIRSWT	TPS3420DDRYR	TPS61252DSGR						
BQ24308DSGT	INA214AIRSWR	TPS3420DDRYT	TPS61252DSGT						
CC2541F256RHAR	INA214AIRSWT	TPS3895ADRYR	TPS62260DRVR						
CC2541F256RHAT	LM27402SQ/NOPB	TPS3895ADRYT	TPS62260DRVT						

INA199A1RSWR	TPS22990DMLR	TPS3897PDRYR	UCC27201ADMR
INA199A1RSWT	TPS22990DMLT	TPS3897PDRYT	UCC27201ADRMT
INA210AIRSWR			



TI Information  
Selective Disclosure

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC2541F256RHAR	Qual Device: INA210AIRSWR	Qual Device: TPS22990DMLR
PC	Preconditioning	Level 1 - 260C	-	3/462/0	-
PC	Preconditioning	Level 2 - 260C	-	-	3/693/0
PC	Preconditioning	Level 3 - 260C	3/693/0	-	-
AC	Autoclave, 121C	96 Hours	3/230/0 <sup>1</sup>	3/231/0	3/231/0
BHAST	Biased HAST, 110C	264 Hours	3/230/0 <sup>2</sup>	-	3/231/0
ED	Electrical Characterization	Side by side	-	3/90/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0	3/231/0
MSL	Moisture Sensitivity	Level 1 - 260C	-	3/36/0	-
MSL	Moisture Sensitivity (Cu Wire)	Level 2 - 260C	-	-	3/36/0
MSL	Moisture Sensitivity (Cu Wire)	Level 3 - 260C	3/36/0	-	-
SA	Salt Atmosphere	24 Hours	3/66/0	-	-
SD	Solderability, Pb-free	Steam age, 8 hours	3/66/0	3/66/0	3/66/0
TC	Temperature Cycle, -65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. site specification)	3/Pass	3/Pass	3/Pass
BPCC	Bond Pad Cratering Check	Post Final Test	3/15/0	3/15/0	3/15/0
DS	Die Shear	Die	3/30/0	-	3/30/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	3/15/0	3/15/0
VM	Visual / Mechanical	(per mfg. site specification)	3/36/0	3/36/0	3/36/0
XRAY	X-Ray	Top side only	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Notes:

1. One device failed post-stress. Bin and failure analysis did not assign root cause to packaging issue, handling, or new factory. Discounted.
2. One device failed post-stress. Unit passed on retest. Discounted.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.